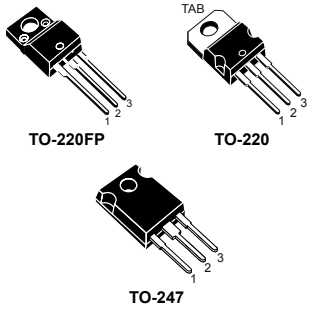
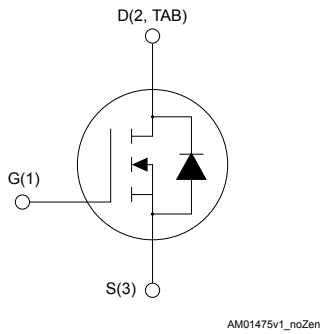
STF18NM60N, STP18NM60N, STW18NM60N

Datasheet

N-channel 600 V, 260 mΩ typ., 13 A MDmesh II Power MOSFETs in TO-220FP, TO-220 and TO-247 packages





Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STF18NM60N	600 V	285 mΩ	13 A
STP18NM60N			
STW18NM60N			

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

Applications

- Switching applications

Description

These devices are N-channel Power MOSFETs developed using the second generation of MDmesh technology. These revolutionary Power MOSFETs associate a vertical structure to the company's strip layout to yield one of the world's lowest on-resistance and gate charge. They are therefore suitable for the most demanding high-efficiency converters.

Product status links
STF18NM60N
STP18NM60N
STW18NM60N

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220 TO-247	TO-220FP	
V_{DS}	Drain-source voltage	600		V
V_{GS}	Gate-source voltage	±25		V
I_D	Drain current (continuous) at T_C = 25 °C	13	13(1)	A
	Drain current (continuous) at T_C = 100 °C	8.2	8.2(1)	
I_{DM}(2)	Drain current (pulsed)	52	52(1)	A
P_{TOT}	Total power dissipation at T_C = 25 °C	110	30	W
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T_C = 25 °C)		2.5	kV
dv/dt(3)	Peak diode recovery voltage slope	15		V/ns
T_{stg}	Storage temperature range	-55 to 150		°C
T_J	Operating junction temperature range			°C

1. *Limited by maximum junction temperature.*
2. *Pulse width limited by safe operating area.*
3. *I_{SD} ≤ 13 A, di/dt ≤ 400 A/µs, V_{DS} (peak) ≤ $V_{(BR)DSS}$, V_{DD} = 480 V.*

Table 2. Thermal data

Symbol	Parameter	Value			Unit
		TO-220	TO-247	TO-220FP	
R_{thJC}	Thermal resistance, junction-to-case	1.14		4.17	°C/W
R_{thJA}	Thermal resistance, junction-to-ambient	62.50	50	62.50	°C/W

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_J max.)	4.5	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	350	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified.

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0 V	600			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 600 V			1	µA
		V_{GS} = 0 V, V_{DS} = 600 V, T_C = 125 °C(1)			10	
I_{GSS}	Gate body leakage current	V_{DS} = 0 V, V_{GS} = ±25 V			±100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 6.5 A		260	285	mΩ

1. *Specified by design, not tested in production.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0 V	-	1000	-	pF
C_{oss}	Output capacitance		-	60	-	pF
C_{rss}	Reverse transfer capacitance		-	3	-	pF
$C_{oss\ eq.}$(1)	Equivalent capacitance time related	V_{DS} = 0 to 480 V, V_{GS} = 0 V	-	225	-	pF
Q_g	Total gate charge	V_{DD} = 480 V, I_D = 13 A, V_{GS} = 0 to 10 V (see the Figure 18. Test circuit for gate charge behavior)	-	35	-	nC
Q_{gs}	Gate-source charge		-	6	-	nC
Q_{gd}	Gate-drain charge		-	20	-	nC
R_g	Intrinsic gate resistance	f = 1 MHz, I_D = 0 A	-	3.5	-	Ω

1. *$C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.*

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 300 V, I_D = 6.5 A, R_G = 4.7 Ω, V_{GS} = 10 V (see the Figure 17. Test circuit for resistive load switching times and Figure 22. Switching time waveform)	-	12	-	ns
t_r	Rise time		-	15	-	ns
$t_{d(off)}$	Turn-off delay time		-	55	-	ns
t_f	Fall time		-	25	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		13	A
I_{SDM}(1)	Source-drain current (pulsed)		-		52	A
V_{SD}(2)	Forward on voltage	I_{SD} = 13 A, V_{GS} = 0 V	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 13 A, di/dt = 100 A/µs, V_{DD} = 60 V (see the Figure 19. Test circuit for inductive load switching and diode recovery times)	-	300		ns
Q_{rr}	Reverse recovery charge		-	4.0		µC
I_{RRM}	Reverse recovery current		-	25		A
t_{rr}	Reverse recovery time	I_{SD} = 13 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_J = 150 °C (see the Figure 19. Test circuit for inductive load switching and diode recovery times)	-	360		ns
Q_{rr}	Reverse recovery charge		-	4.5		µC
I_{RRM}	Reverse recovery current		-	25		A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for TO-220FP

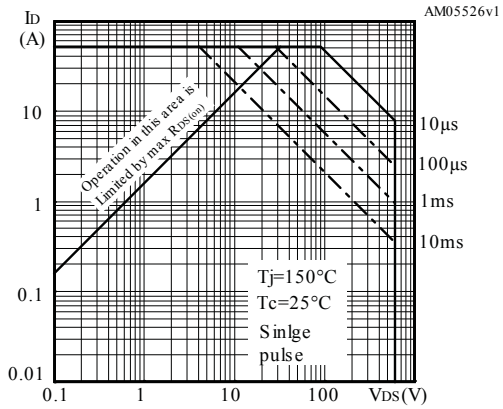


Figure 2. Normalized transient thermal impedance for TO-220FP

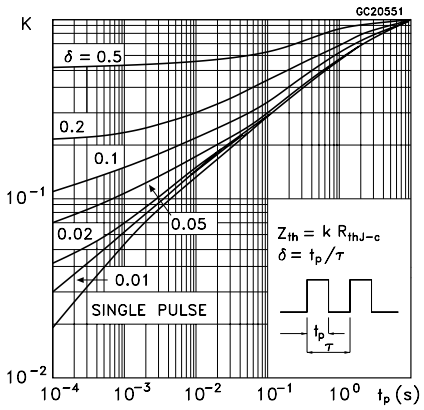


Figure 3. Safe operating area for TO-220

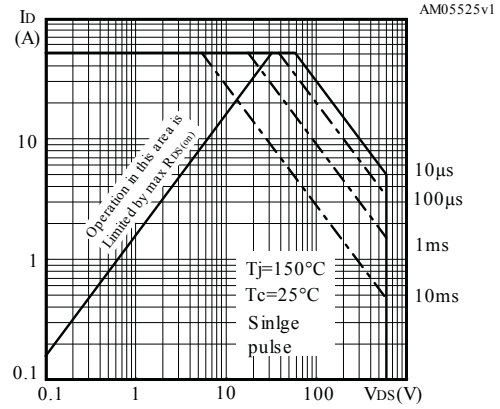


Figure 4. Normalized transient thermal impedance for TO-220

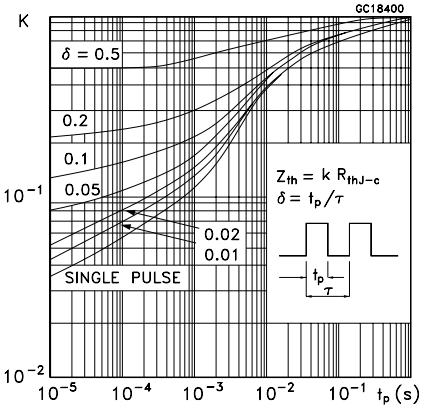


Figure 5. Safe operating area for TO-247

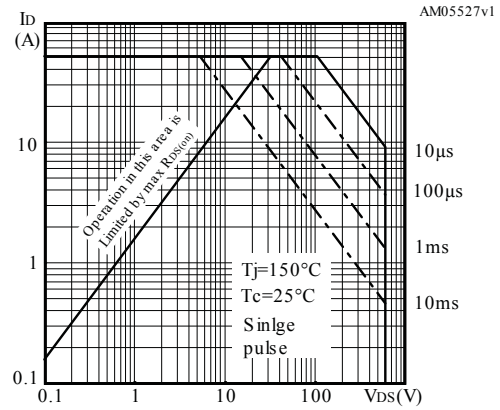


Figure 6. Normalized transient thermal impedance for TO-247

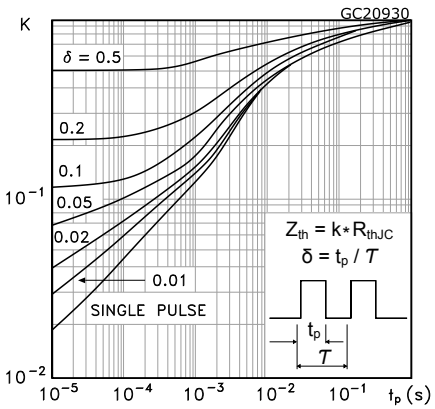


Figure 7. Typical output characteristics

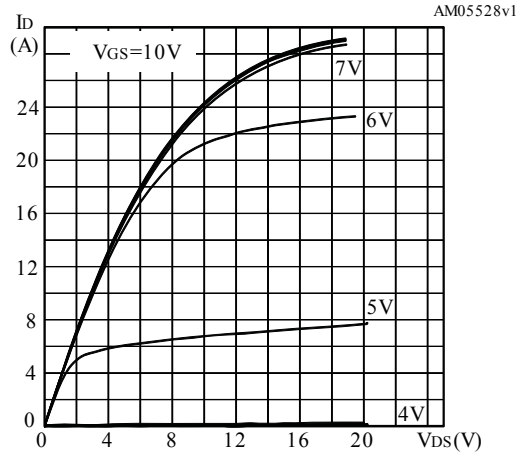


Figure 8. Typical transfer characteristics

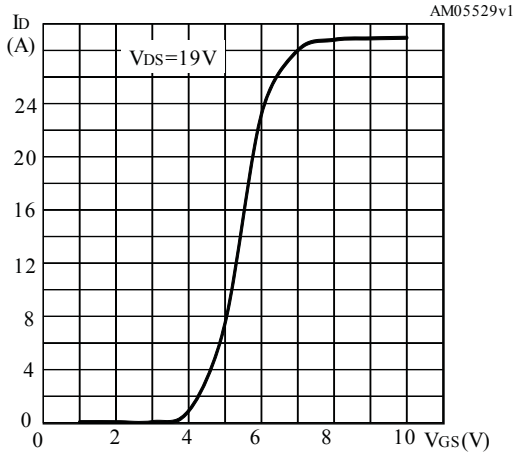


Figure 9. Typical gate charge characteristics

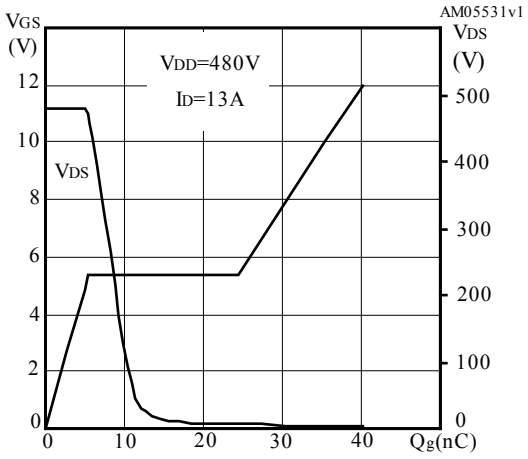


Figure 10. Typical capacitance characteristics

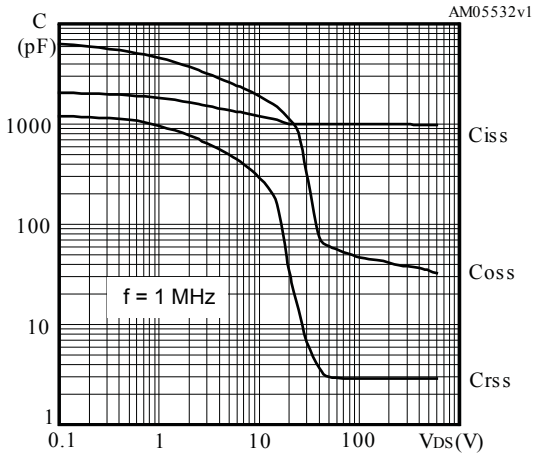


Figure 11. Typical drain-source on-resistance

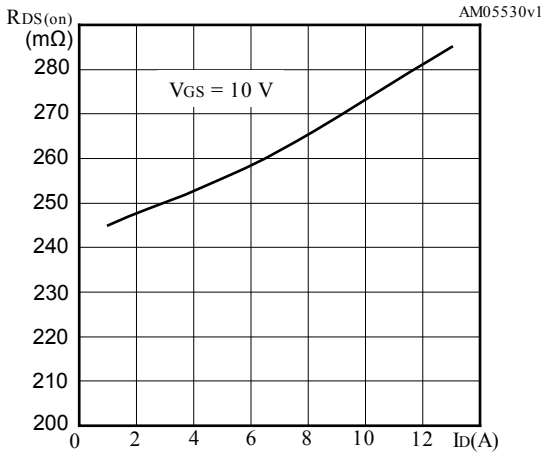


Figure 12. Normalized breakdown voltage vs temperature

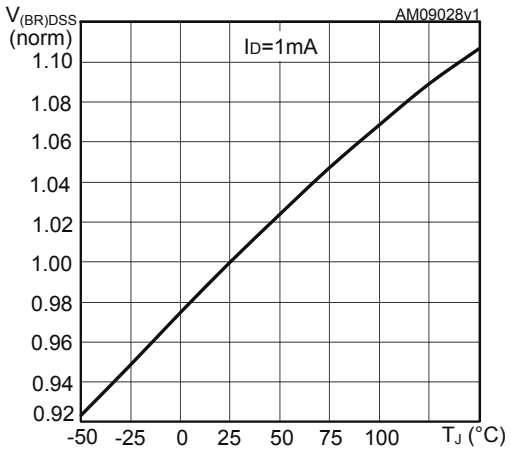


Figure 13. Normalized gate threshold vs temperature

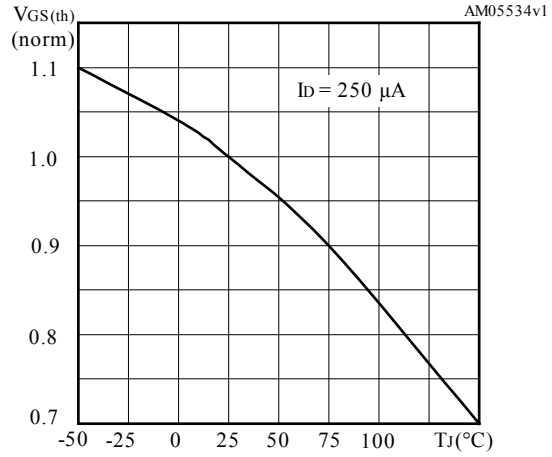


Figure 14. Normalized on-resistance vs temperature

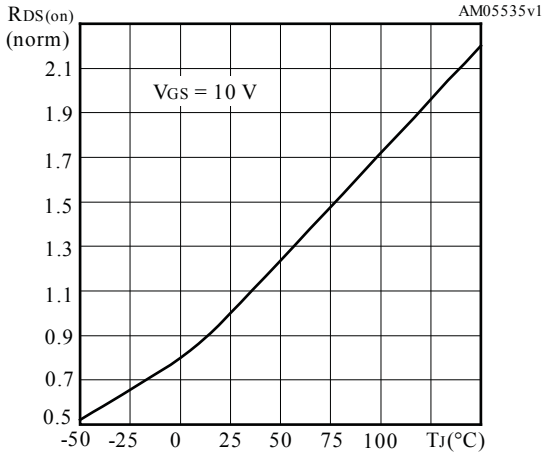


Figure 15. Typical reverse diode forward characteristics

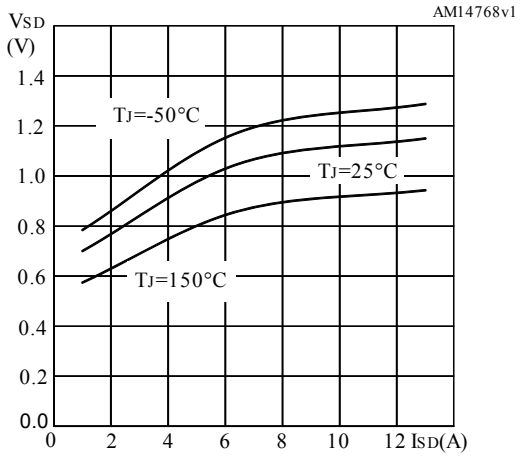
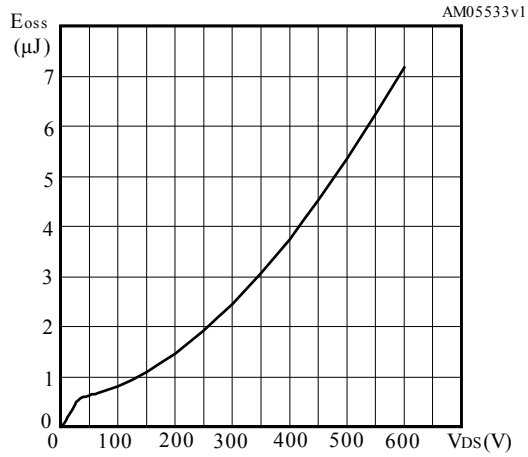


Figure 16. Typical output capacitance stored energy



3 Test circuits

Figure 17. Test circuit for resistive load switching times

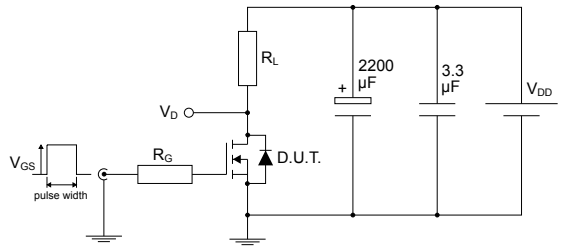


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Figure 18. Test circuit for gate charge behavior

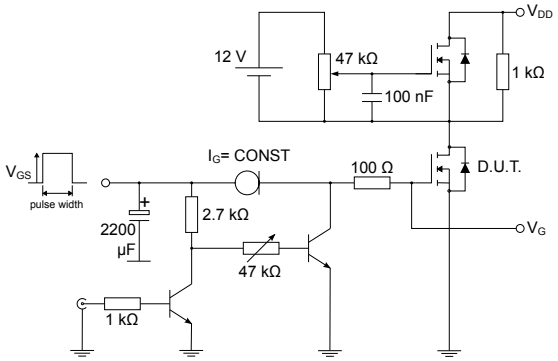

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Figure 19. Test circuit for inductive load switching and diode recovery times

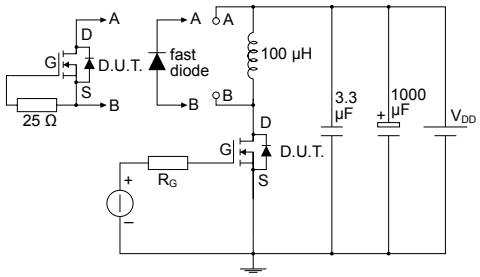

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Figure 20. Unclamped inductive load test circuit

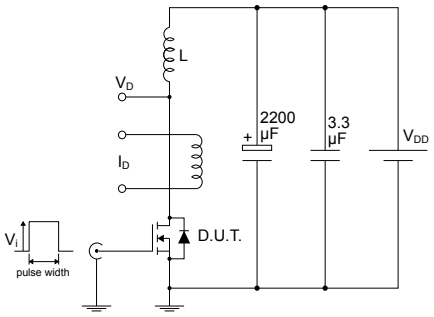

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Figure 21. Unclamped inductive waveform

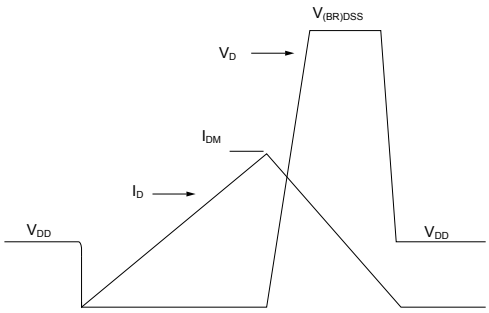

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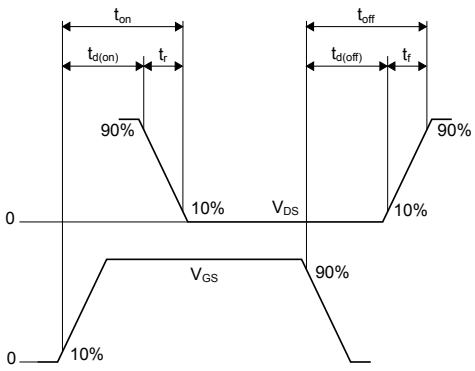
Figure 22. Switching time waveform



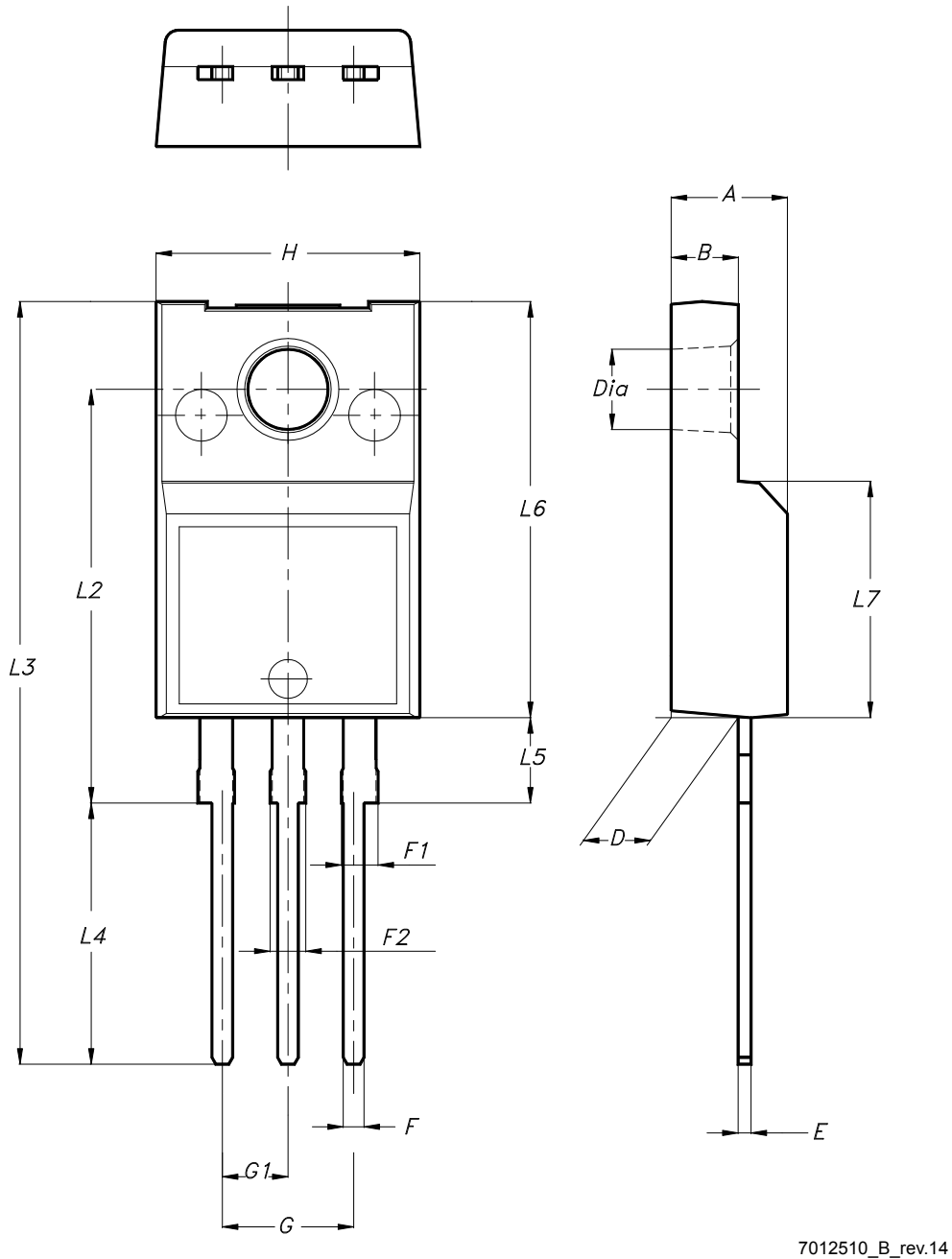
AM01473v1

4 Package information

To meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-220FP type B package information

Figure 23. TO-220FP type B package outline



7012510_B_rev.14

Table 8. **TO-220FP type B package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

4.2 TO-220 type A package information

Figure 24. **TO-220 type A package outline**

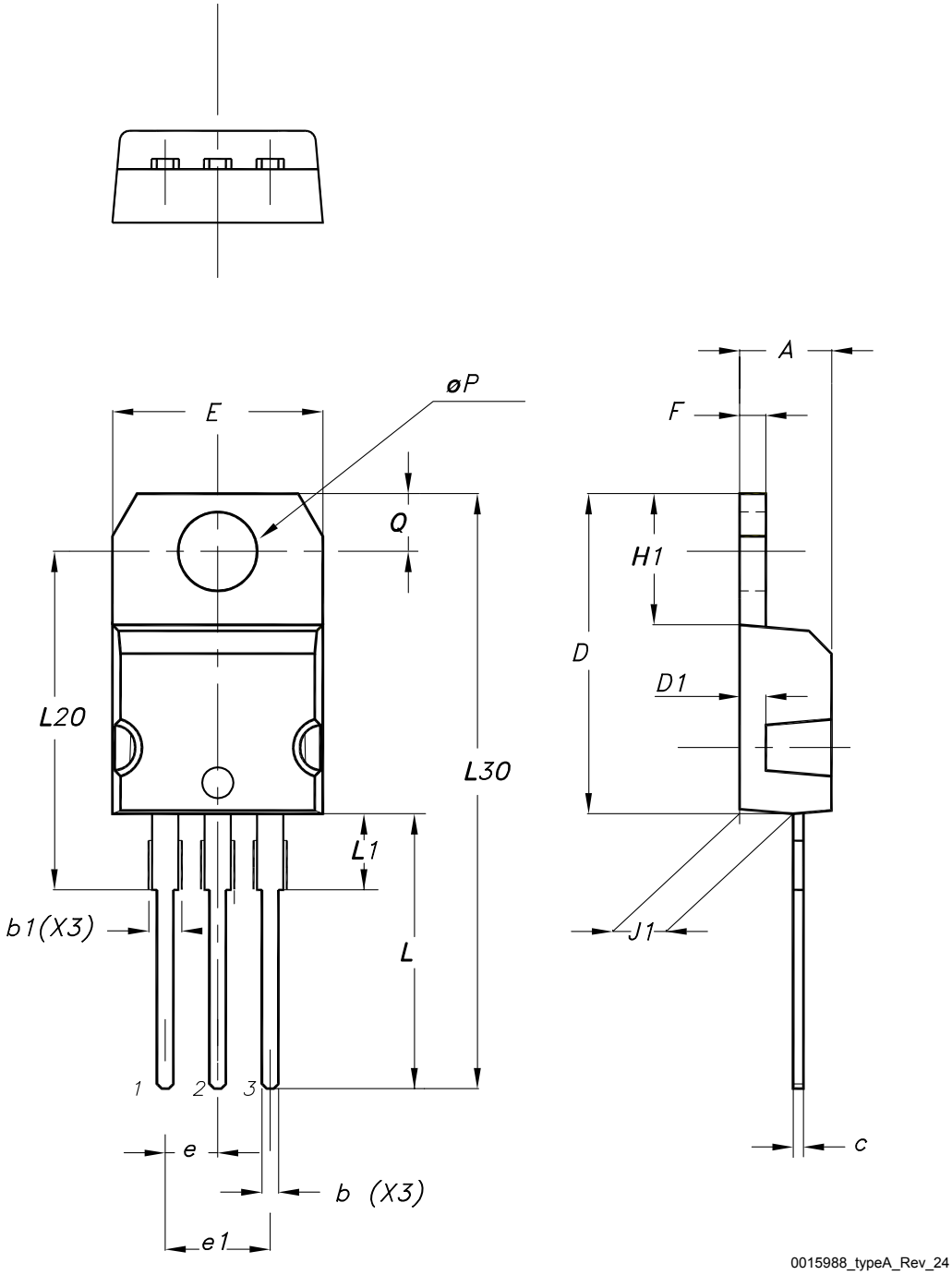
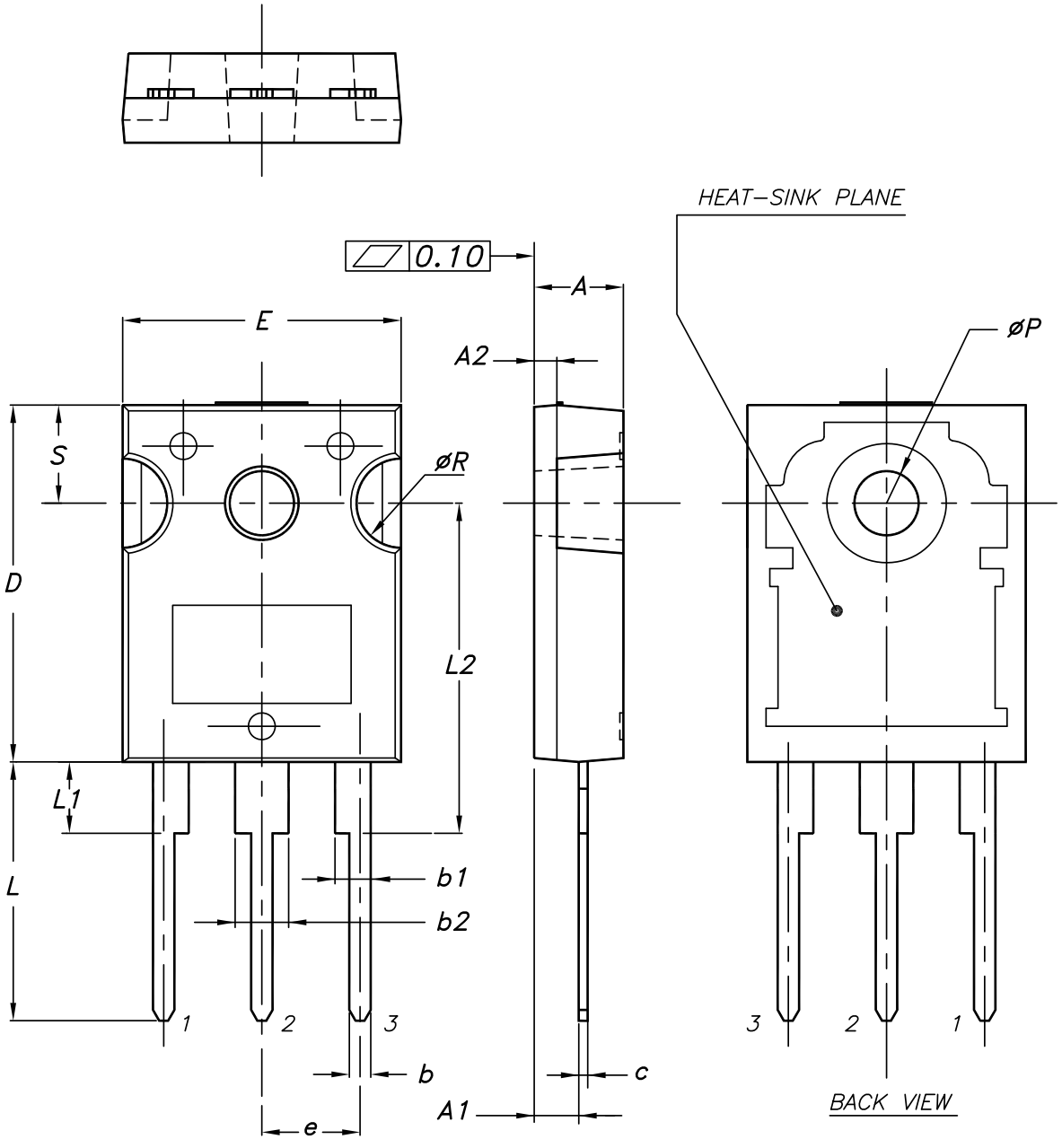


Table 9. **TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

4.3 TO-247 package information

Figure 25. **TO-247 package outline**



0075325_11

Table 10. **TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
A2		1.27	
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

5 Ordering information

Table 11. **Order codes**

Order codes	Marking	Package	Packing
STF18NM60N	18NM60N	TO-220FP	Tube
STP18NM60N		TO-220	
STW18NM60N		TO-247	

Revision history

Table 12. **Document revision history**

Date	Revision	Changes
15-Jun-2009	1	First release.
11-Nov-2009	2	– Added $R_{DS(on)}$ typical value – Added new package, mechanical data: I²PAK – Document status promoted from preliminary data to datasheet
06-Oct-2010	3	Inserted new value in *Table 5*.
01-Oct-2012	4	Updated title and description on the cover page. Updated *figures 10*, *11*, *14*, *15* and *16*. Updated *Section 4: Package mechanical data* and *Section 5: Packaging mechanical data*.
09-Mar-2026	5	The part number STB18NM60N have been removed and the document has been updated accordingly. Updated Section 4: Package information. Minor text changes.

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